Title: Datasheet for LM25119Q					
<b>Customer Contact:</b> PCN Man	<u>ager</u>		De	ept: Quality Services	
Change Type:					
Assembly Site		Design		Wafer Bump Site	
Assembly Process	$\boxtimes$	Data Sheet		Wafer Bump Material	
Assembly Materials		Part number change		Wafer Bump Process	
Mechanical Specification		Test Site		Wafer Fab Site	
Packing/Shipping/Labeling		Test Process	Ш	Wafer Fab Materials	
				Wafer Fab Process	
Notification Details					
Description of Change:					
Texas Instruments Incorporated is announcing an information only notification.  The product datasheet(s) is being updated as summarized below.  The following change history provides further details.					
TEXAS INSTRUMENTS LM25119Q					
- HOHOMEIVIS				SLUSD97 - APRIL 2018	
DATE		DE MOLON		NOTES	
DATE		REVISION	Initi	NOTES ial release. Previously included with the	
April 2018		*		M25119 data sheet. To view previous revision history, see SNVS680.	
The datasheet number will be changing.					
Device Family		Change From:		Change To:	
LM25119Q		SNVS676I		SLUSD97	
These changes may be reviewed at the datasheet links provided.					
http://www.ti.com/product/LM25119Q					
Reason for Change:					
To accurately reflect device characteristics.					
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):					
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.					
Changes to product identification resulting from this PCN:					
None.					
Product Affected:					

PCN Date:

June 15, 2018

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

LM25119QPSQX/NOPB

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com

LM25119QPSQ/NOPB

**PCN Number:** 

20180612001